CLAIMS

1	1. A method for fabricating a magnetic head comprising the steps of:
2	fabricating a write head portion of said magnetic head, including the steps of:
3	fabricating first magnetic pole;
4	fabricating an insulation layer above said first magnetic pole;
5	depositing a seed layer upon said insulation layer;
6	electroplating an induction coil upon said seed layer;
7	removing portions of said seed layer that are not covered by said induction coil,
8	utilizing a RIE process;
9	wherein said RIE process utilizes fluorine species, and said seed layer is
10	comprised of a material that forms a gaseous compound with said fluorine species.
1	2. A method for fabricating a magnetic head as described in claim 1 wherein said seed layer
2	is comprised of a material selected from the group consisting of tungsten and titanium.
1	3. A method for fabricating a magnetic head as described in claim 2 wherein said seed layer
2	has a thickness of approximately 500 Å to 800 Å
1	4. A method for fabricating a magnetic head as described in claim 2 wherein said seed layer
2	is fabricated in a sputter deposition process.

- 1 5. A method for fabricating a magnetic head as described in claim 2 wherein said RIE
- 2 process utilizes a compound selected from the group consisting of CF₄, CHF₃, SF₆, C₂F₆ and
- 3 C_3F_8 to provide said fluorine ion species.
- 1 6. A method for fabricating a magnetic head as described in claim 1 wherein said induction
- 2 coil is composed of copper, and wherein said seed layer includes and an upper part comprised of
- 3 copper and a lower portion comprised of a material selected from the group consisting of
- 4 tungsten, titanium and tantalum, and wherein said induction coil is electroplated upon said
- 5 copper upper portion of said seed layer.
- 1 7. A method for fabricating a magnetic head comprising the steps of:
- 2 fabricating a write head portion of said magnetic head, including the steps of:
- 3 fabricating a first magnetic pole;
- 4 fabricating a seed layer above said first magnetic pole;
- 5 electroplating a second magnetic pole upon said seed layer;
- 6 removing portions of said seed layer that are not covered by said second magnetic
- 7 pole utilizing a RIE process;
- 8 wherein said RIE process utilizes fluorine ion species, and said seedlayer is
- 9 comprised of a material that forms a gaseous compound with said fluorine ion species.
- 1 8. A method for fabricating a magnetic head as described in claim 7 wherein said seed layer
- 2 is comprised of a material selected from the group consisting of tungsten and titanium.

- 1 9. A method for fabricating a magnetic head as described in claim 8 wherein said seed layer
- 2 has a thickness of approximately 500 Å to 800 Å.
- 1 10. A method for fabricating a magnetic head as described in claim 8 wherein said seed layer
- 2 is fabricated in a sputter deposition process.
- 1 11. A method for fabricating a magnetic head as described in claim 7 wherein said RIE
- 2 process utilizes a compound selected from the group consisting of CF₄, CHF₃, SF₆, C₂F₆ and
- 3 C_3F_8 to provide said fluorine ion species.
- 1 12. A method for fabricating a magnetic head as described in claim 7 wherein said second
- 2 magnetic pole is composed of NiFe, and wherein said seed layer is fabricated to include an upper
- 3 part comprised of NiFe and a lower part comprised of a material selected from the group
- 4 consisting of tungsten, titanium and tantalum, and wherein said second magnetic pole is
- 5 electroplated upon said NiFe upper portion of said seed layer.
- 1 13. A method for fabricating a magnetic head as described in claim 7 wherein said seed layer
- 2 is fabricated upon said first magnetic pole.
- 1 14 A method for fabricating a magnetic head as described in claim 13 wherein said seed
- 2 layer is a write gap layer disposed between said first magnetic pole and said second magnetic
- 3 pole.

- 1 15. A magnetic head comprising:
- 2 a write head portion,
- an insulation layer being disposed within said write head portion;
- 4 a seed layer being disposed upon said insulation layer,
- 5 an induction coil being disposed upon said insulation layer;
- said seed layer being comprised of a material selected from the group consisting of
- 7 tungsten, tantalum and titanium.
- 1 16. A magnetic head as described in claim 15 wherein said seed layer is formed with a
- 2 thickness of approximately 500 Å to 800 Å.
- 1 17. A magnetic head as described in claim 15 wherein said induction coil is comprised of
- 2 copper, and wherein said seed layer is comprised of a lower part and a copper upper part,
- 3 wherein said lower part is disposed upon said insulation layer, and said induction coil is disposed
- 4 upon said copper part.
- 1 18. A magnetic head as described in claim 17 wherein said lower part of said seed layer is
- 2 formed with a thickness of approximately 500 Å to 800 Å, and said copper part of said seed layer
- 3 is formed with a thickness of approximately 100 Å.
- 1 19. A magnetic head comprising:
- 2 a write head portion including a first magnetic pole and a second magnetic pole;

- a seed layer being disposed between said first magnetic pole and said second magnetic
- 4 pole, said second magnetic pole being disposed upon said seed layer;
- said seed layer being comprised of a material selected from the group consisting of
- 6 tungsten, tantalum and titanium.
- 1 20. A magnetic head as described in claim 19 wherein said seed layer is formed with a
- 2 thickness of approximately 500 Å to 2,000 Å.
- 1 21. A magnetic head as described in claim 19 wherein said second magnetic pole is
- 2 comprised of an NiFe, and wherein said seed layer includes a lower part and an upper part
- 3 comprised of NiFe, and wherein said second magnetic pole is disposed upon said NiFe upper
- 4 part of said seed layer.
- 1 22. A magnetic head as described in claim 21 wherein said NiFe upper part of said seed layer
- 2 is formed with a thickness of approximately 100 Å, and said lower part of said seed layer is
- 3 formed with a thickness of approximately 500 Å to 2,000 Å.
- 1 23. A hard disk drive comprising:
- at least one hard disk being adapted for rotary motion upon a disk drive;
- at least one magnetic head being adapted to fly over said hard disk for writing data on
- 4 said hard disk, said magnetic head including:
- 5 a write head portion,
- an insulation layer being disposed within said write head portion;

- 7 a seed layer being disposed upon said insulation layer,
- 8 an induction coil being disposed upon said insulation layer;
- 9 said seed layer being comprised of a material selected from the group consisting of
- tungsten, tantalum and titanium.
- 1 24. A hard disk drive as described in claim 23 wherein said seed layer is formed with a
- 2 thickness of approximately 500 Å to 800 Å.
- 1 25. A hard disk drive as described in claim 23 wherein said induction coil is comprised of
- 2 copper, and wherein said seed layer is comprised of a copper part and a lower part, wherein said
- 3 lower part is disposed upon said insulation layer, and said induction coil is disposed upon said
- 4 copper part.
- 1 26. A hard disk drive as described in claim 25 wherein said lower part of said seed layer is
- 2 formed with a thickness of approximately 500 Å to 800 Å, and said copper part of said seed layer
- 3 is formed with a thickness of approximately 100 Å.
- 1 27. A hard disk drive comprising:
- at least one hard disk being adapted for rotary motion upon a disk drive;
- at least one magnetic head being adapted to fly over said hard disk for writing data on
- 4 said hard disk, said magnetic head including:
- 5 a write head portion including a first magnetic pole and a second magnetic pole;

- a seed layer being disposed between said first magnetic pole and said second magnetic
- 7 pole, said second magnetic pole being disposed upon said seed layer;
- 8 said seed layer being comprised of a material selected from the group consisting of
- 9 tungsten, tantalum and titanium.
- 1 28. A hard disk drive as described in claim 27 wherein said seed layer is formed with a
- 2 thickness of approximately 500 Å to 2,000 Å.
- 1 29. A hard disk drive as described in claim 27 wherein said second magnetic pole is
- 2 comprised of an NiFe, and wherein said seed layer includes a lower part and an upper part
- 3 comprised of NiFe, and wherein said second magnetic pole is disposed upon said NiFe upper
- 4 part of said seed layer.
- 1 30. A hard disk drive as described in claim 29 wherein said NiFe upper part of said seed
- 2 layer is formed with a thickness of approximately 100 Å, and said lower part of said seed layer is
- 3 formed with a thickness of approximately 500 Å to 2,000 Å.